

Call for Papers
a Session on

Smart and Sustainable Manufacturing

2016 ASME/ISCIE International Symposium on Flexible Automation (ISFA2016)
InterContinental Hotel & Conference Center
August 1-3, 2016, Cleveland, Ohio, USA

Session Technical Focus

The quest for sustainable manufacturing requires knowledge-based and data-driven approaches that exploit the wealth of information available to improve manufacturing processes/systems at minimum environmental, economic and societal costs. We cordially invite you to submit a paper to share your knowledge and expertise in all areas related to **Smart and Sustainable Manufacturing**. Papers from the industrial sector are particularly encouraged. The session welcomes both theoretical and applied papers in areas including, but not limited to:

- Smart and sustainable manufacturing systems, equipment and technologies
- Next-generation, intelligent robotics and automation
- Energy efficient manufacturing systems, equipment and technologies
- Mechatronic systems for smart and sustainable manufacturing
- Cloud-enabled manufacturing systems and applications
- Internet of Things, Industry 4.0 and/or Industrial Internet for manufacturing
- Assessment and monitoring of smart and sustainable manufacturing technologies

Paper Submission

The deadline for submission of your contribution to this session is **February 29, 2016**. Both short and long papers will be considered and reviewed. For short papers, please submit a summary of 1,000 words or less (short papers will be limited to 4 pages) and, for long papers, please submit a manuscript of no more than eight pages. All summaries and manuscripts should be submitted through the conference website at <http://engineering.case.edu/conference/ISFA2016/>.

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